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(54) Title: EPOXY COMPOUND AND CURED EPOXY RESIN PRODUCT

(57) Abstract: The present invention provides a novel epoxy compound, which can be converted into a cured epoxy resin product having liquid crystal properties by curing with a curing agent. Since the cured epoxy resin product of the present invention exhibits good heat conductivity, it is also useful as an insulating material requiring high heat releasability such as a printed circuit substrate and the like.

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